Name COLLEGE

Reg. No....

## EIGHTH SEMESTER B.TECH. (ENGINEERING) DEGREE EXAMINATION JUNE 2008

EC 2 K 803-MICROELECTRONICS TECHNOLOG

Time: Three Hours

Maximum 100 Mark

- I. (a) Explain the principle of water processing, with a neat sketch.
  - (b) Why Optical exposures are preferred for microelectronic devices? Explain.
  - (c) Give an account on "Device and Isolation".
  - (d) Explain the advantages of schottky contacts.
  - (e) Enumerate and explain the advantages and applications of CMOs technology.
  - (f) Enumerate and explain the BICMOS fabrication process.
  - (g) Explain the layout of MOSFET with a neat sketch.
  - (h) Explain the design rules for well and pads.

 $(8 \times 5 = 40 \text{ marks})$ 

II. (a) (i) Explain the principle of optical lithography in detail with neat sketches.

(7 marks)

(ii) Explain the MOCVD process with neat sketches.

(8 marks)

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- (b) Explain the following:—
  - (1) Fick's law.

- (2) Channelling.
- (3) Deal-grove model.

 $(3 \times 5 = 15 \text{ marks})$ 

III. (a) Explain in detail the LOCOS and SWAMI processes with neat diagrams.

Or

- (b) Describe in detail the advantages of schottky contacts and Implanted ohmic contacts with neat sketches.
- IV. (a) Describe in detail the CMOS fabrication process sequence with neat sketches.

Or

- (b) Explain in detail the hot carrier effects in BJT and CMOS with neat sketches.
- V. (a) Explain in detail the layouts of NAND and NOR gates with neat sketches.

Or

- (b) Write short notes on.
  - (1) Layout of junction Isolated BJT.

(7 marks

(8 marks

(2) Layout using Cell hierarchy.

 $(4 \times 15 = 60 \text{ marks})$ 

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